

MAX40109 Evaluation System

Evaluates: MAX40109

General Description

The MAX40109 evaluation system (EV system) demonstrates the precision sensor conditioning analog front end (AFE) for pressure sensors. The MAX40109 EV system includes the MAX40109 EV kit and the MAX32666FTHR board. Windows®-compatible software provides a graphical user interface (GUI) to demonstrate the features of the MAX40109. The GUI supports I²C, SPI, and 1-Wire® communication.

The MAX40109 EV kit PCB comes with a MAX40109IATP+ installed which is the I^2C and 1-Wire variant IC.

Features and Benefits

- On-Board Microcontroller (MAX32666) to Evaluate the MAX40109
- Accommodates Easy-to-Use Components
- Proven PCB Layout
- Fully Assembled and Tested

Quick Start

Required Equipment

- MAX40109 EV System (USB Cable Included)
- Windows PC
- 3V to 36V, 100mA DC Power Supply
- 2.75V to 6V, 100mA DC Power Supply
- Two DC Voltage Sources
- Voltmeter
- MAX40109EVkitSetupVXXX.zip File

Note: In the following sections, software-related items are identified by bolding. Text in bold refers to items directly from the EV kit software. Text in bold and underlined refers to items from the Windows operating system.

Procedure

Procedure for Voltage Output

The MAX40109 EV kit is fully assembled and tested. Follow the steps below to verify board operation.

- Set the 3V to 36V supply to 5V. Connect the positive terminal of the 3V to 36V supply to the VDDHV test point and the negative terminal to the AGND test point of the EV kit, respectively.
- Measure the voltage at the VDD5V test point.
- Set the 2.75V to 6V supply to the voltage measured at the VDD5V test point. Connect the positive terminal of the second supply to the VDDA5 test point and the negative terminal to the DGND test point of the EV kit, respectively.
- Connect the first DC voltage source at INP- and AGND test points. Set the DC source to 1V. Connect the second DC voltage source at INP+ and INP- test points. Set the DC source to 20mV.
- Connect the voltmeter between the OUT and AGND test points.
- Verify all the shunts are in the default position as shown in *Table 1*.
- Turn on the power supplies and DC voltage sources.
- Start the MAX40109 GUI as shown in Figure 1.
- Within the Register Settings tab sheet, start by selecting Bypass (Raw Mode) from the Pressure Cal dropdown list within the Configuration Register group box. The default PGA Gain is set to 10. Select 8 from the Analog Output Stage dropdown list on the right. Click the Set All button when the desired settings are finalized.
- Monitor the voltage at the OUT test point.

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1-Wire is a registered trademark of Maxim Integrated Products, Inc.

Ordering Information appears at end of data sheet.

MAX40109 Evaluation System

MAX40109 EV System Photo



Procedure for Current Output

The MAX40109 EV kit is fully assembled and tested. Follow the steps below to verify board operation.

- Remove the bypass capacitors C5 and C6. The VDDHV supply ground changes to the EXT test point.
- Set the 3V to 36V supply to 5V. Connect the positive terminal of the 3V to 36V supply to the VDDHV test point and the negative terminal to the EXT test point of the EV kit, respectively.
- Measure the voltage at the VDD5V test point.
- Set the 2.75V to 6V supply to the voltage measured at the VDD5V test point. Connect the positive terminal of the second supply to the VDDA5 test point and the negative terminal to the DGND test point of the EV kit, respectively.
- Connect the first DC voltage source at the INN and AGND test points. Set the DC source to 1V.
- Connect the second DC voltage source at INP+ and INP- test points. Set the DC source to 100mV.
- The jumpers at the output stage should be placed as follow:
 - J4: 1-2 position
 - · J6: 2-3 position
 - J8: Installed
 - J10: Installed
- Turn on the power supplies and DC voltage sources.
- Start the MAX40109 GUI as shown in <u>Figure 1</u>.
- Within the Register Settings tab sheet, start by selecting Bypass (Raw Mode) from the Pressure Cal dropdown list within the Configuration Register group box. The default PGA Gain is set to 10. Select 7 from the Analog Output Stage dropdown list on the right. Click Set All button when the desired settings are finalized.
- Monitor the voltage between the EXT and AGND test point. The measured voltage is divided by 50Ω (R11) and the value here is the current at the output. The expected current is 4mA.
- Repeat from Step 6 but adjust the DC calibrator from 20mV to 100mV. The expected current is 20mA.

MAX40109 Evaluation System

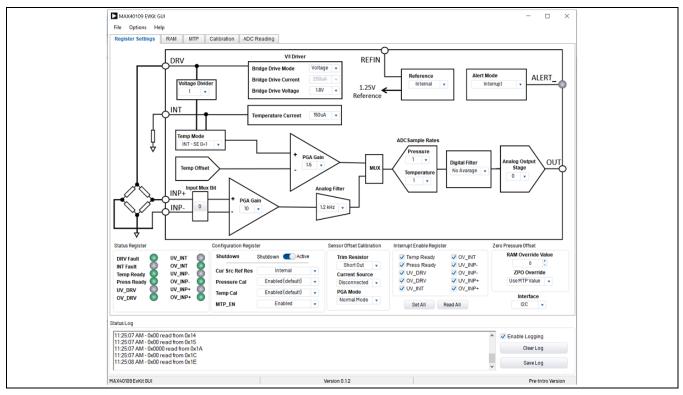


Figure 1. MAX40109 EV System GUI Main Window (Register Setting Tab)

Table 1. MAX40109 EV System Jumper Descriptions

JUMPER	SHUNT POSITION	DESCRIPTION			
J3	1-2*	I ² C SDA connection to the on-board microcontroller.			
12	2-3	SPI DIN connection to the on-board microcontroller.			
J4	1-2*	FB+ connection.			
04	2-3	SPI DSO connection to the on-board microcontroller.			
J5	Installed	Connects the 5V supply from the USB supply. The AGND ground must be externally connected to the microcontroller ground.			
33	Not installed*	User-supplied VDDHV. User must apply 3V to 36V at VDDHV. Disconnects the 5V from the USB supply.			
J6	1-2	SPI CSB connection to the on-board microcontroller.			
10	2-3*	FB- connection.			
J7	1-2*	I ² C SCL connection to the on-board microcontroller.			
57	2-3	SPI SCLK connection to the on-board microcontroller.			
J8	Installed	Connects collector of the transistor to VDDHV.			
10	Not installed*	Disconnects collector of the transistor to VDDHV.			
J9	1-2*	Connects the thermistor to the INT pin.			
00	2-3	Connects AGND to the INT pin.			

J10	Installed*	Connects the OUT pin to the base of transistor Q1.
510	Not installed	Disconnects the OUT pin to the base of transistor Q1.
J11	Installed*	Connects ALERT to the on-board microcontroller.
511	Not installed	Disconnects ALERT to the on-board microcontroller.
J12	1-2	1-Wire DQ connection to the on-board microcontroller.
512	2-3	Connects to VDD5V for I ² C and PLC communications.
J13	1-2	User-supplied 5V supply to isolators.
	2-3*	VDD5V supply to the isolators.

*Default position.

Detailed Description of Hardware

The MAX40109 EV system demonstrates the precision sensor conditioning AFE for pressure sensors. The MAX40109 EV system consist of two boards; the MAX40109 EV kit and the MAX32666FTHR board.

I²C Interface

To evaluate the EV kit with a user-supplied I²C bus, the jumpers J3 and J7 must not have shunts installed. Apply the user-supplied I²C to the SDA/DIN and SCL/SCLK test points, respectively. Make sure the return ground is DGND.

1-Wire Interface

To evaluate the EV kit with a user-supplied 1-Wire bus, jumper J12 must not have a shunt installed. Applied the usersupplied 1-Wire to the DQ test point. Make sure the return ground is DGND.

ALERT

To evaluate the EV kit with a user-supplied ALERT, jumper J11 must not have a shunt installed. Apply the user-supplied ALERT to the ALERT test point.

Detailed Description of Software

The main window of the MAX40109 EV kit software contains controls to evaluate the MAX40109 IC. There are five tabs to demonstrate the features of the part. The **Register Settings** tab allows for a user-friendly access to the RAM register. The **RAM** and **MTP** tabs display a bit view of the register map. The **Calibration** tab allows the user to prototype coefficients before burning into MTP. The **ADC Reading** tab allows for sample collection of pressure and temperature in a time domain.

Register Settings Tab

The **Register Settings** tab (*Figure 1*) displays the control of the frequently used RAM registers. In addition, the user can select the digital interface from I²C, SPI,1-Wire, and VDDHV. Once the interface is selected, a pop-up window appears to ensure the user places the appropriate jumper settings on the EV kit. The SPI and VDDHV selections should not be used for now and are intended for future use. Once the desired settings are configured, the user needs to click the **Set All** button.

RAM Tab

The **RAM** tab displays all RAM registers in a bit view (*Figure 2*). This tab is helpful in verifying the data of each RAM register. Refer to the MAX40109 IC data sheet for a detailed description of the RAM registers.

	egister Settings RAM MTF	Callor	ation ADC Rea	aung					
Configuration 0x00 16 RWV 0x0000 Y Status 0x02 12 RVW 0x000 Y PGA Pressure Gain 0x04 8 RVW 0x00 Y Uncatibrated Pressure 0x06 16 RO 0x0000 Y Uncatibrated Pressure 0x06 16 RO 0x0000 Y Uncatibrated Pressure 0x06 16 RO 0x0000 Y Uncatibrated Temperature 0x08 16 RO 0x0000 Y Interrupt Enable 0x06 10 RVW 0x0 Y PGA Temperature Gain 0x04 8 RVW 0x0 Y Catibrated Pressure 0x0F 16 RO 0x0000 Y Catibrated Temperature 0x11 16 RO 0x0000 Y Sensor Offset Cal Config 0x14 R RVW 0x00 Y SLP_MREF 0x96 16 RVW 0x00	Display Type: Hexadec	imal							
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Winds Winds Winds Winds Winds PGAFPressure Gain 0.04 8 R/W 0.00 Y Uncalibrated Pressure 0.05 3 R/W 0.00 Y Uncalibrated Pressure 0.06 16 RO 0.00000 Y Uncalibrated Temperature 0.06 16 RO 0.00000 Y ADC Sample Rate 0.06 16 RO 0.00000 Y Interrupt Enable 0.06 10 R/W 0.00 Y Rod Sample Rate 0.00E 8 R/W 0.000 Y Calibrated Pressure 0.00E 8 R/W 0.000 Y Calibrated Pressure 0.011 16 RO 0.0000 Y Zero Press. Offset RAM Override 0.11A 16 R/W 0.000 Y SLP_MR 0.99D 16 R/W 0.000 Y CP_Control_1 0.96P 8 R/W 0.000 Y MPP_Control 0.42 8 R/W 0.000 Y	Configuration	0x00	16	R/W	0x0000				
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	MTP_PROT_ADDR	0xA4	8	R/W	0x00	~			
:02:24 PM - 0x00 read from 0x14	MTP_PROT_ADDR	-	-			 ~			
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0224 PM - 0x000 read from 0x1C 0224 PM - 0x000 read from 0x1C SaveLon									olda Log

Figure 2. MAX40109 EV System GUI Main Window (RAM Tab)

MTP Tab

The **MTP** tab displays the MTP registers in a bit view (*Figure 3*). This tab is helpful in verifying the data of each MTP register. Always click the **Initialize** button before writing or burning into MTP. The user should be careful with the **Burn** button since there is a limited number of burns to the MTP register. Refer to the MAX40109 IC data sheet for a detailed description of the MTP registers.

Evaluation Board User Guide

Register Settings	RAM	P Calibration	n ADC	Reading						
							MTP Configurations			
							Diagnostic Range		Diag Data	
Display Type:	Hexadecima	il .					Upper	Lower	Over Pressure +	0 +
Reg Name	Addr	Num of Bits	R/W	Value	Select	^ Desel All	Enable 0	0	Under Pressure +	0 +
CAL_DATA0	0x00	16	R/W	0x0000			Clipping Threshold		Over Volt. Temp.	0 +
CAL_DATA1	0x01	16	R/W	0x0000		Read	Upper	Lower	Under Volt. Temp.	0 +
CAL_DATA2	0x02	16	R/W	0x0001		Write	Enable 0 🏥	0 🗄	Over Pressure -	0 *
CAL_DATA3	0x03	16	R/W	0x0000			Pressure Threshold			
CAL_DATA4	0x04	16	R/W	0x0000		Burn			Under Pressure -	U _
CAL_DATA5	0x05	16	R/W	0x0000		Initialize	Primary Pressure	0 🗄	Over Voltage Drive	- v
CAL_DATA6	0x06	16	R/W	0x0000			Hysteresis Pressure	0 📫	Under Voltage Drive	0 📩
CAL_DATA7	0×07	16	R/W	0x0000		Save to File	Miscellaneous			
CAL_DATA8	0x08	16	R/W	0x0000		Read from File				
CAL_DATA9	0x09	16	R/W	0x0000			Voltage Divider	•	ADC Sample Ra Pressure	ates
CAL_DATA10	0x0A	16	R/W	0x0000			Temp Mode	•	riessure	
CAL_DATA11	0x0B	16	R/W	0x0000			Bridge Drive		Temperature	
CAL_DATA12	0x0C	16	R/W	0x0000			Bridge D. Cur.		Temperature	
CAL_DATA13	0x0D	16	R/W	0x0000						
CAL_DATA14	0x0E	16	R/W	0x0000			Config MTP			
CAL_DATA15	0x0F	16	R/W	0x0000			MTP Lock An	alog Output		
CAL_DATA16	0×10	16	R/W	0x0001			ZPO Enabled	Stage	Read	Initialize
CAL_DATA17	0x11	16	R/W	0x0000			Sensor Polarity	0 📩	Write	Burn
CAL_DATA18	0x12	16	R/W	0x0000						
CAL_DATA19	0×13	16	R/W	0x0000						
CAL_DATA20	0x14	16	R/W	0x0000						
CAL_DATA21	0x15	16	R/W	0x0000						
CAL_DATA22	0x16	16	R/W	0x0000						
CAL_DATA23	0×17	16	R/W	0x0000		*				
atus Log 5:02:24 PM - 0x00 rea 5:02:24 PM - 0x00 rea 5:02:24 PM - 0x00 rea 5:02:24 PM - 0x00 rea 5:02:24 PM - 0x00 rea	ad from 0x15 read from 0x1 ad from 0x1C	A							↑ ✓ Enable Log Clear Save	Log

Figure 3. MAX40109 EV System GUI Main Window (MTP Tab)

Calibration Tab

The **Calibration** tab displays the coefficients within the MTP registers. This tab is useful for prototyping coefficients before burning into MTP. Always click the **Initialize** button before writing or burning into MTP. The user should be careful with the **Burn** button since there is a limited number of burns to the MTP register.

Below are the steps to calibrate for temperature.

- Within the Register Settings tab sheet, start by selecting Bypass (Raw Mode) from the Temp Cal dropdown list within the Configuration Register group box. Next, select the desired PGA Gain, V/I Driver, ADC Sample Rates for Temperature, and Sensor Offset Calibration options. Lastly, select the desired temperature measurement option from INT or DRV in the Temp Mode dropdown list. Click Set All button when desired settings are finalized.
- Within the RAM tab sheet, read the Uncalibrated Temperature (0x08) register. Record codes at desired temperature range. Used the codes to create coefficient for K0–K3.
- Within the Calibration tab sheet, enter the user's coefficients within the T0 and Pout group box. Enter 0 for any coefficients that are not used. Once set, click the Initialize button followed by the Write button. The user can write to the coefficient register as many times as possible to make changes. Only click the Burn button if the coefficients are finalized.
- Return to the **Register Setting** tab sheet. Select **Enabled (default)** from the **Temp Cal** dropdown list within the **Configuration Register** group box. Click the **Set All** button.
- Within the **RAM** tab sheet, read the **Calibrated Temperature (0x11)** register. Record the codes at the desired temperature and compare with the initial uncalibrated temperature.

Below are the steps to calibrate for pressure.

- Within the Register Settings tab sheet, start by selecting Bypass (Raw Mode) from the Pressure Cal dropdown list within the Configuration Register group box. Next, select the desired PGA Gain, ADC Sample Rates for Pressure, and Bridge Drive options. Lastly, make sure the Sensor Offset Calibration options are left at Trim Resistor-Connected, Current Source-Disconnected, and PGA Mode-Normal. Click the Set All button when the desired settings are finalized.
- Within the **MPT** tab, enable the zero-pressure offset by entering 0x404D to the **CONFIG MTP** (0x44) register. Once set, click the **Initialize** button followed by the **Write** button.
- Within the MTP tab sheet, enter the value field of the ZERO_PRESSURE_OFFSET (0x3D) register. Refer to the Zero
 Pressure Offset section of the MAX40109 IC data sheet for details on how to obtain the offset. Once set, click the
 Initialize button followed by the Write button.
- Within the RAM tab sheet, read the Uncalibrated Pressure (0x06) register. Record the data.
- Within the **Calibration** tab sheet, enter the user's coefficients within the **T0** and **Pout** group box. Enter 0 for any coefficient that is not used. Once set, click the **Initialize** button followed by the **Write** button. The user can write to the coefficient register as many times as possible to make changes. Only click the **Burn** button if the coefficients are finalized.
- Return to the **Register Setting** tab sheet. Select **Enabled (default)** from the **Pressure Cal** dropdown list within the **Configuration Register** group box. Click the **Set All** button.
- Within the **RAM** tab sheet, read the **Calibrated Pressure (0x0F)** register. Record codes at desired pressure and compare with the initial uncalibrated pressure.

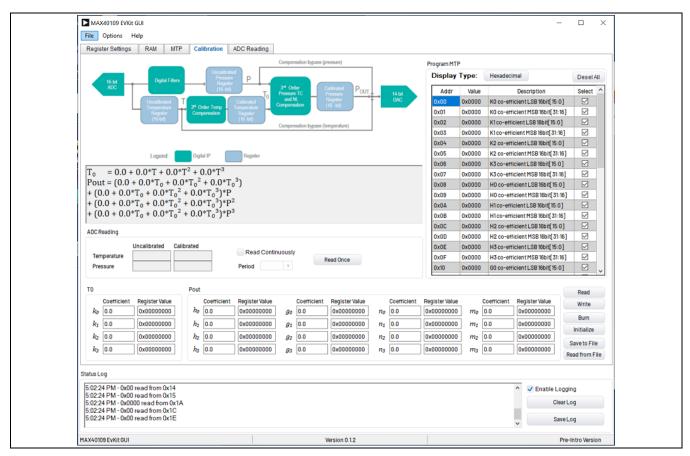


Figure 4. MAX40109 EV System GUI Main Window (Calibration Tab)

ADC Reading Tab

The **ADC Reading** tab displays the readings from the calibrated/uncalibrated pressure and temperature of the RAM registers.

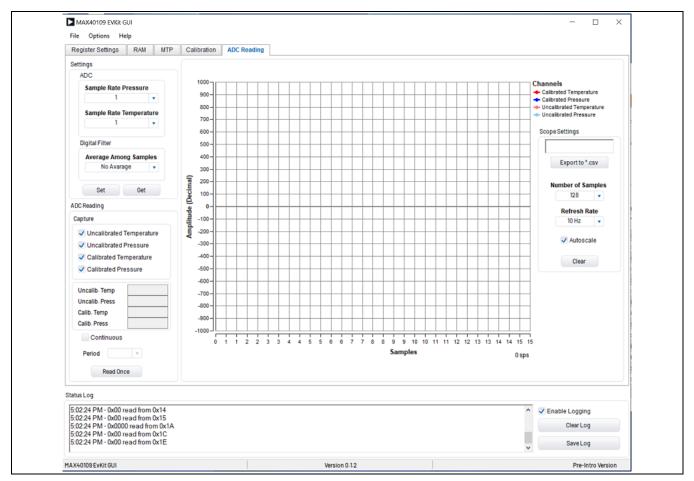


Figure 5. MAX40109 EV System GUI Main Window (ADC Reading Tab)

Ordering Information

PART	ТҮРЕ
MAX40109ITEVSYS1#	EV System (EV Kit and Microcontroller Board)

Denotes RoHS-compliant.

Component List

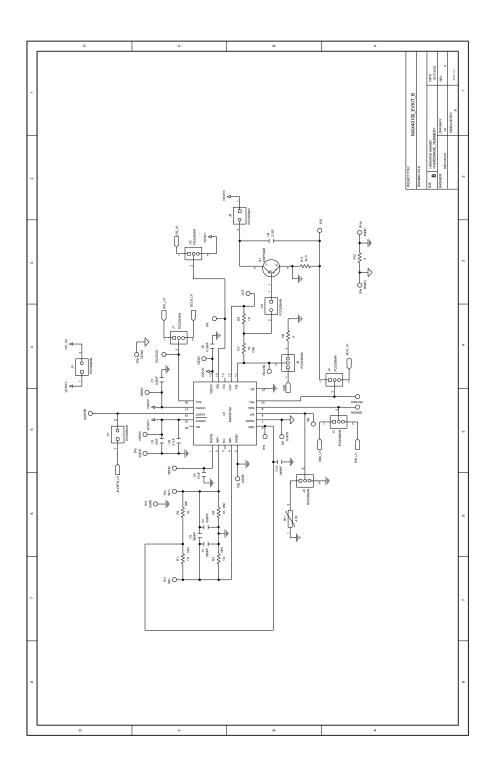
ITEM	REF_D ES	DNI/ DNP	QT Y	MANUFACTURER PART NUMBER	MANUFACTURER	VALUE	DESCRIPTION
1	ALERT B, DQ, EXT, FB+/S DO, FB- /CSB, INT, OUT, SCL/S CLK, SDA/DI N, TP1, TP4, TP6	_	12	5012	KEYSTONE	N/A	TEST POINT; PIN DIA=0.125IN; TOTAL LENGTH=0.445I N; BOARD HOLE=0.063IN; WHITE; PHOSPHOR BRONZE WIRE SILVER PLATE FINISH;
2	C2, C16	_	2	06035C102KAT2AL;C1608X7R1H102K080 AE	AVX;TDK	1000PF	CAP; SMT (0603); 1000PF; 10%; 50V; X7R; CERAMIC
3	C4, C6, C9- C15	_	9	C0603C104K5RAC;C1608X7R1H104K;EC J- 1VB1H104K;GRM188R71H104KA93;CGJ3 E2X7R1H104K080AA;C1608X7R1H104K0 80AA;CL10B104KB8NNN;CL10B104KB8N FN;06035C104KAT2A;06035C104KAT4A	KEMET;TDK;PANAS ONIC;MURATA;TDK; TDK;SAMSUNG;SAM SUNG;AVX;AVX	0.1UF	CAP; SMT (0603); 0.1UF; 10%; 50V; X7R; CERAMIC;
4	C5	_	1	CC0805KKX5R9BB106;GRM21BR61H106 KE43	YAGEO;MURATA	10UF	CAP; SMT (0805); 10UF; 10%; 50V; X5R; CERAMIC
5	C7, C8	_	2	C1608X7R1H224K080; GRM188R71H224KAC4	TDK;MURATA	0.22UF	CAP; SMT (0603); 0.22UF; 10%; 50V; X7R; CERAMIC
6	J1	_	1	PPPC121LFBN-RC	SULLINS ELECTRONICS CORP	PPPC12 1LFBN- RC	CONNECTOR; FEMALE; THROUGH HOLE; HEADER FEMALE; STRAIGHT; 12PINS
7	J2		1	PPPC161LFBN-RC	SULLINS ELECTRONICS CORP.	PPPC16 1LFBN- RC	CONNECTOR; FEMALE; THROUGH HOLE; LFB SERIES; 2.54MM CONTACT CENTER;

ITEM	REF_D ES	DNI/ DNP	QT Y	MANUFACTURER PART NUMBER	MANUFACTURER	VALUE	DESCRIPTION
							STRAIGHT; 16PINS
8	J3, J4, J6, J7, J9, J12, J13		7	PCC03SAAN	SULLINS	PCC03S AAN	CONNECTOR; MALE; THROUGH HOLE; BREAKAWAY; STRAIGHT THROUGH; 3PINS; -65 DEGC TO +125 DEGC
9	J5, J8, J10, J11		4	PCC02SAAN	SULLINS	PCC02S AAN	CONNECTOR; MALE; THROUGH HOLE; BREAKAWAY; STRAIGHT THROUGH; 2PINS; -65 DEGC TO +125 DEGC
10	MH1- MH4	_	4	9032	KEYSTONE	9032	MACHINE FABRICATED; ROUND-THRU HOLE SPACER; NO THREAD; M3.5; 5/8IN; NYLON
11	Q1	_	1	CMPT6428	CENTRAL SEMICONDUCTOR	CMPT64 28	TRANSISTOR, NPN, SOT-23, PD=0.35W, IC=0.2A, VCEO=60V
12	R8, R12	_	2	RC1608J000CS;CR0603-J/- 000ELF;RC0603JR-070RL	SAMSUNG ELECTRONICS;BOU RNS;YAGEO PH	0	RES; SMT (0603); 0; 5%; JUMPER; 0.1000W
13	R9	_	1	ERJ-3GEYJ102	PANASONIC	1K	RES; SMT (0603); 1K; 5%; +/- 200PPM/DEGC; 0.1000W
14	R11	_	1	CRCW060349R9FK	VISHAY DALE	49.9	RES; SMT (0603); 49.9; 1%; +/- 100PPM/DEGC; 0.1000W
15	R13- R28	_	16	ERJ-3GEYJ472	PANASONIC	4.7K	RES; SMT (0603); 4.7K; 5%; +/-

ITEM	REF_D ES	DNI/ DNP	QT Y	MANUFACTURER PART NUMBER	MANUFACTURER	VALUE	DESCRIPTION
							200PPM/DEGC; 0.1000W
16	REFIN, VDD2V , VDD5V , VDDA5 , VDDH V	_	5	5010	KEYSTONE	N/A	TEST POINT; PIN DIA=0.125IN; TOTAL LENGTH=0.445I N; BOARD HOLE=0.063IN; RED; PHOSPHOR BRONZE WIRE SIL;
17	RT1	_	1	TFPT0805L4701FV	VISHAY	4.7K	THERMISTOR; SMT (0805); 4.7K; TOL=+/-1%
18	TP2, TP3, TP5, TP7- TP12		9	5011	KEYSTONE	N/A	TEST POINT; PIN DIA=0.125IN; TOTAL LENGTH=0.445I N; BOARD HOLE=0.063IN; BLACK; PHOSPHOR BRONZE WIRE SILVER PLATE FINISH;
19	U1		1	MAX40109IATP+	ANALOG DEVICES	MAX401 09IATP+	EVKIT PART - IC; SNSR; PRECISION SENSOR CONDITIONING AFE FOR PRESSURE SENSORS; PACKAGE CODE:T2044- 5C; PACKAGE OUTLINE DRAWING:21- 0139; PACKAGE LAND PATTERN:90- 0429; TQFN20- EP
20	U3, U5	_	2	MAX14933ASE+	ANALOG DEVICES	MAX149 33ASE+	IC; ISO; TWO- CHANNEL; 2.75KV I2C ISOLATOR; NSOIC16

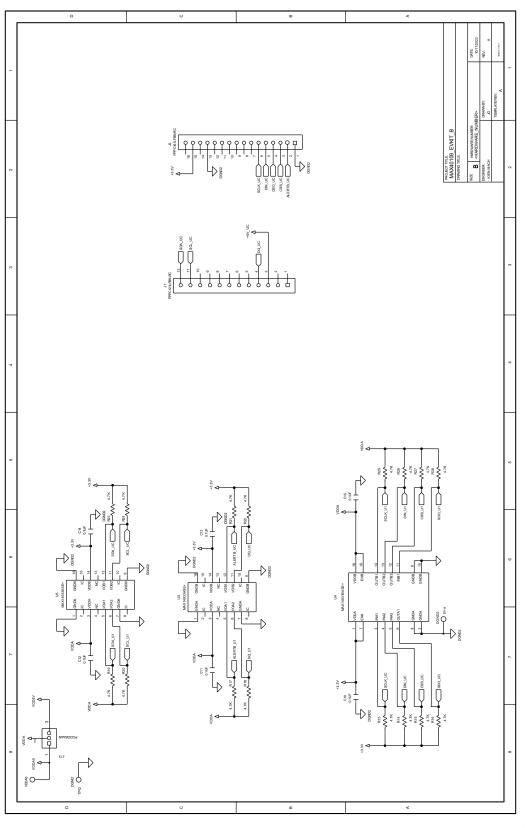
ITEM	REF_D ES	DNI/ DNP	QT Y	MANUFACTURER PART NUMBER	MANUFACTURER	VALUE	DESCRIPTION
21	U4		1	MAX14931BASE+	ANALOG DEVICES	MAX149 31BASE +	IC; DISO; 3/1 CHANNEL; 25MBPS; 2.75KVRMS DIGITAL ISOLATOR; NSOIC16 150MIL
22	PCB	_	1	MAX40109	ANALOG DEVICES	PCB	PCB:MAX
23	C1, C3	DNP	0	06035C102KAT2AL;C1608X7R1H102K080 AE	AVX;TDK	1000PF	CAP; SMT (0603); 1000PF; 10%; 50V; X7R; CERAMIC
24	R1–R4, R7	DNP	0	ERJ-3GEYJ102	PANASONIC	1K	RES; SMT (0603); 1K; 5%; +/- 200PPM/DEGC; 0.1000W

MAX40109 EV System Schematic

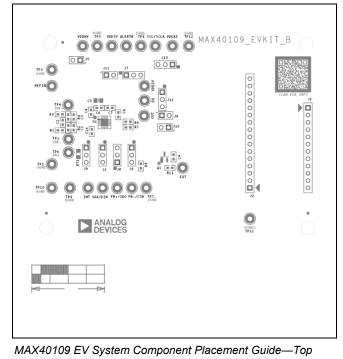


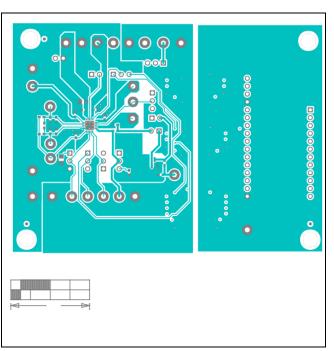
Evaluation Board User Guide

MAX40109 Evaluation System



MAX40109 EV System Layout





MAX40109 EV System PCB Layout—Layer 2

0 **D**O **D**OO 0 0 0 Ο 0 00 0 000 0 0 • 0 0 0 0 0 0 0 0

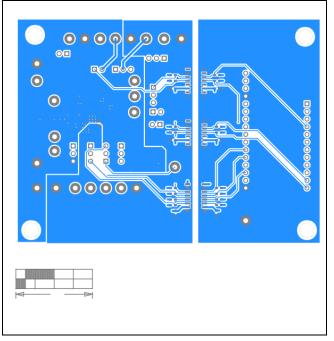
MAX40109 EV System PCB Layout—Layer 3

MAX40109 EV System PCB Layout—Top

analog.com

Silkscreen

MAX40109 EV System PCB Layout (continued)



MAX40109 EV System PCB Layout—Bottom

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0 0 0 0 0 0 0 0 0 0
••

MAX40109 EV System Component Placement Guide—Bottom Silkscreen

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGE(S) CHANGED
0	10/23	Initial release	—
1	10/23	Removed individual boards from Ordering Information section	8

MAX40109 Evaluation System

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